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(12) **United States Design Patent** (10) **Patent No.:** **US D772,172 S**  
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(54) **SIGNAL I/O MODULE**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/162**; D13/147

(58) **Field of Classification Search**  
USPC ..... D13/123, 133, 146, 147, 149, 154, D13/162.1, 184, 199; 439/74, 108, 180, 439/252, 258, 246, 278, 374, 378-379, 381, 439/527, 529, 533, 660, 717, 865-894, 953, 439/135, 144, 139-141, 147, 136, 638, 518, 439/131, 271; 174/16.3; 257/697, 727; 361/769; D14/435, 356, 242, 436, 433, D14/474, 240, 496, 385, 358, 480.1-480.7, D14/125, 388, 203.4; 360/97.01, 685-686, 360/752, 737, 732, 784, 803; 365/51, 63, 365/131; 710/52, 300, 313; 711/115, 103, 711/154, 161-162; 70/58; 323/210; 713/186, 1; 382/124

CPC ..... H05K 2201/10; H05K 2201/10007; H05K 2201/216; H01R 13/62933; H01R 13/62905; H01R 13/6275; H01R 13/6395; H01R 13/62938; H01R 13/64; H01R 13/645;

H01R 13/6456; H01R 13/635; H01R 13/633; H01R 23/7005; H01R 23/682; H01R 23/684; H01R 23/70; H01R 23/7068; H01R 23/7026  
See application file for complete search history.

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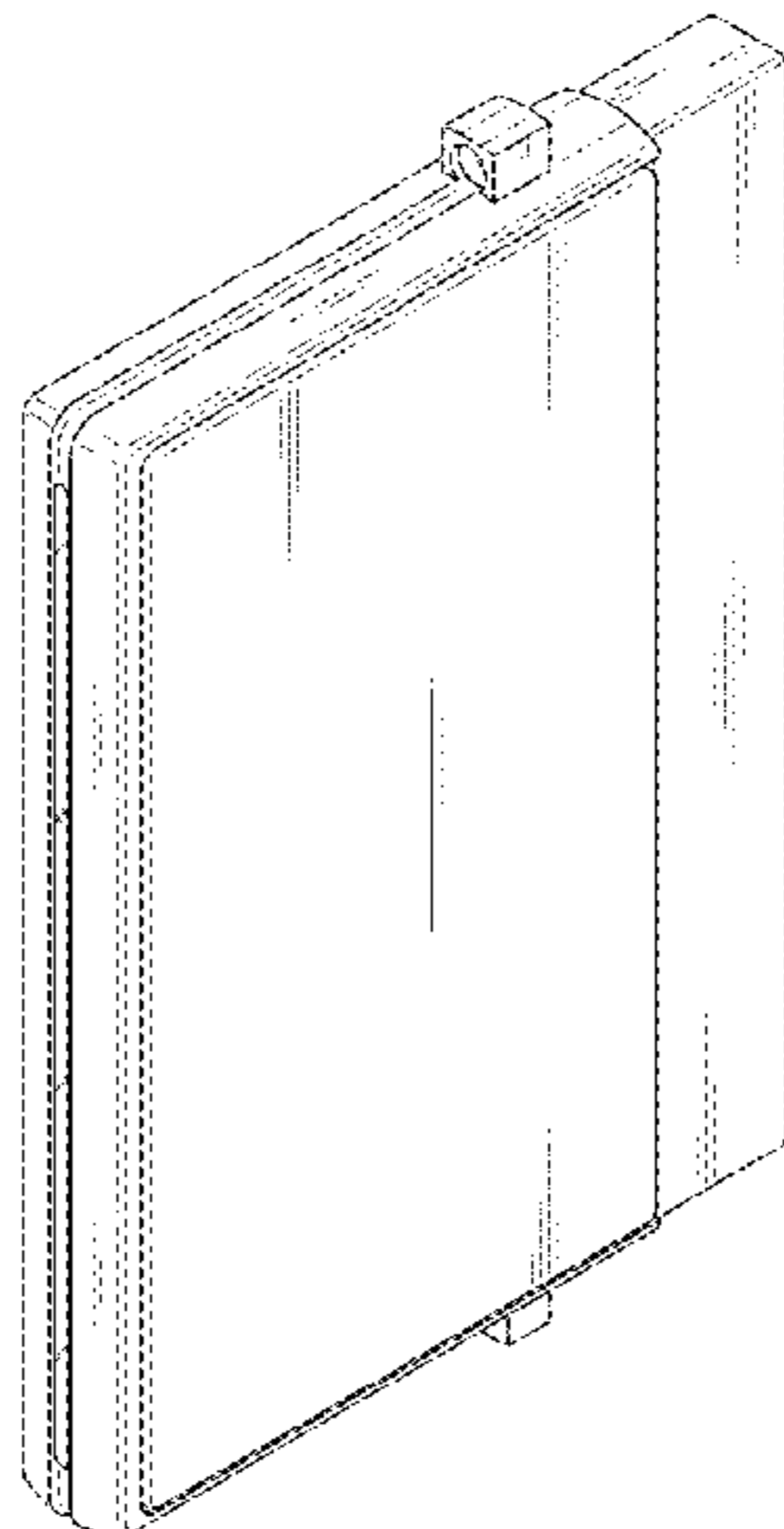
(57) **CLAIM**

The ornamental design for a signal I/O module, as shown and described.

**DESCRIPTION**

FIG. 1 is a front perspective view of a signal I/O module showing our new design;  
FIG. 2 is a front view thereof;  
FIG. 3 is a rear view thereof;  
FIG. 4 is a left side view thereof;  
FIG. 5 is a right side view thereof;  
FIG. 6 is a top view thereof;  
FIG. 7 is a bottom view thereof; and,  
FIG. 8 is a perspective view thereof in use.  
The broken lines shown are included for the purpose of illustrating the unclaimed portions of the signal I/O module and form no part of the claimed design.

**1 Claim, 6 Drawing Sheets**



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Fig. 1

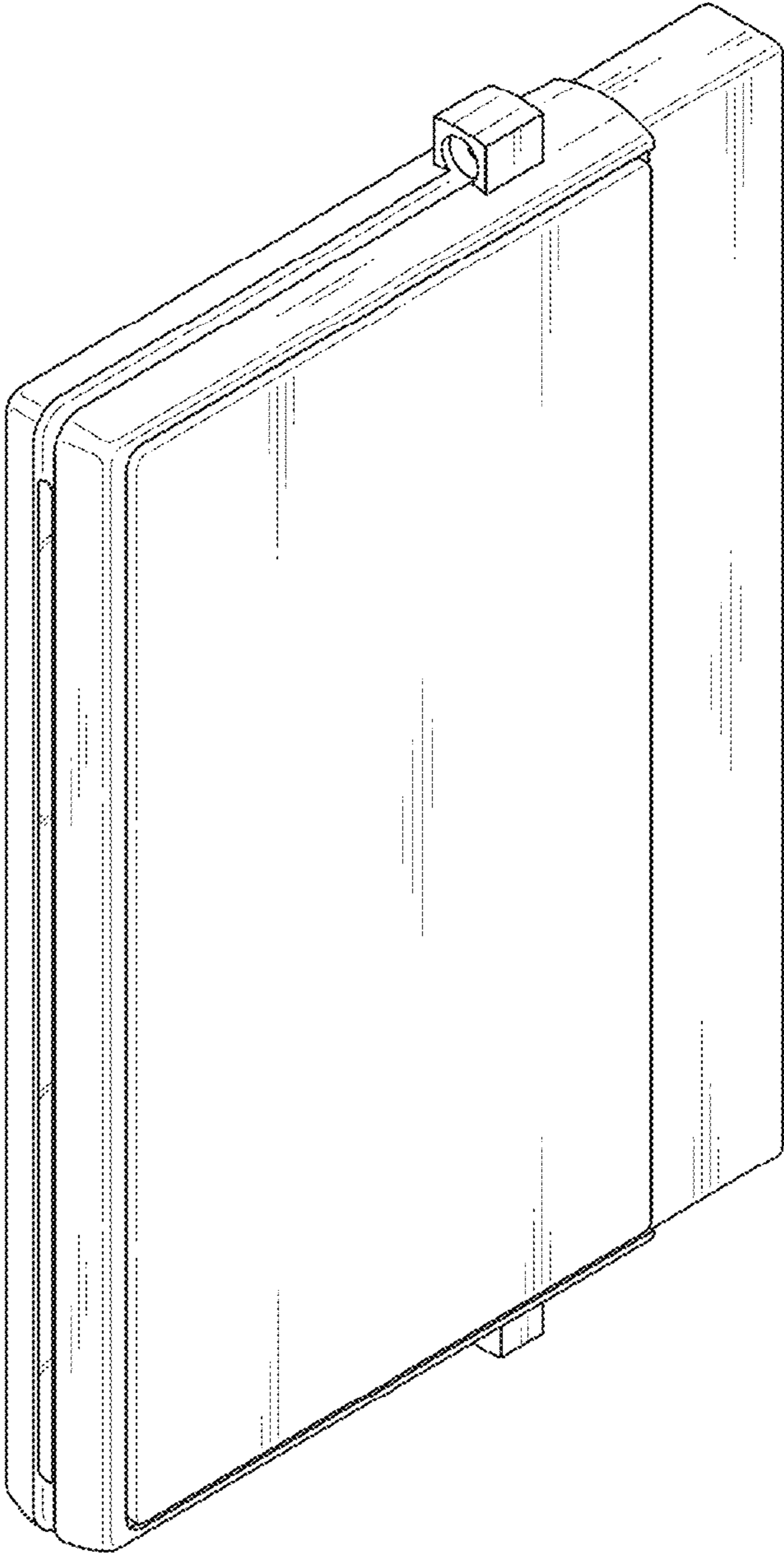


Fig. 2

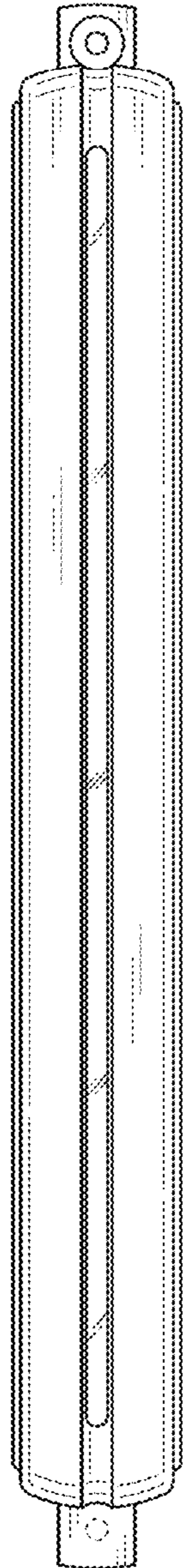


Fig. 3

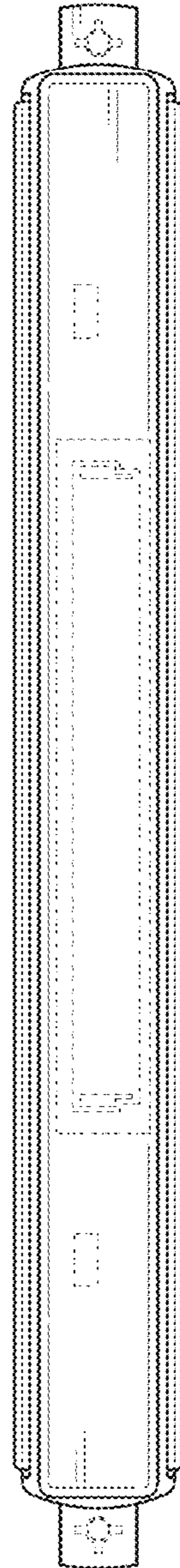


Fig. 4

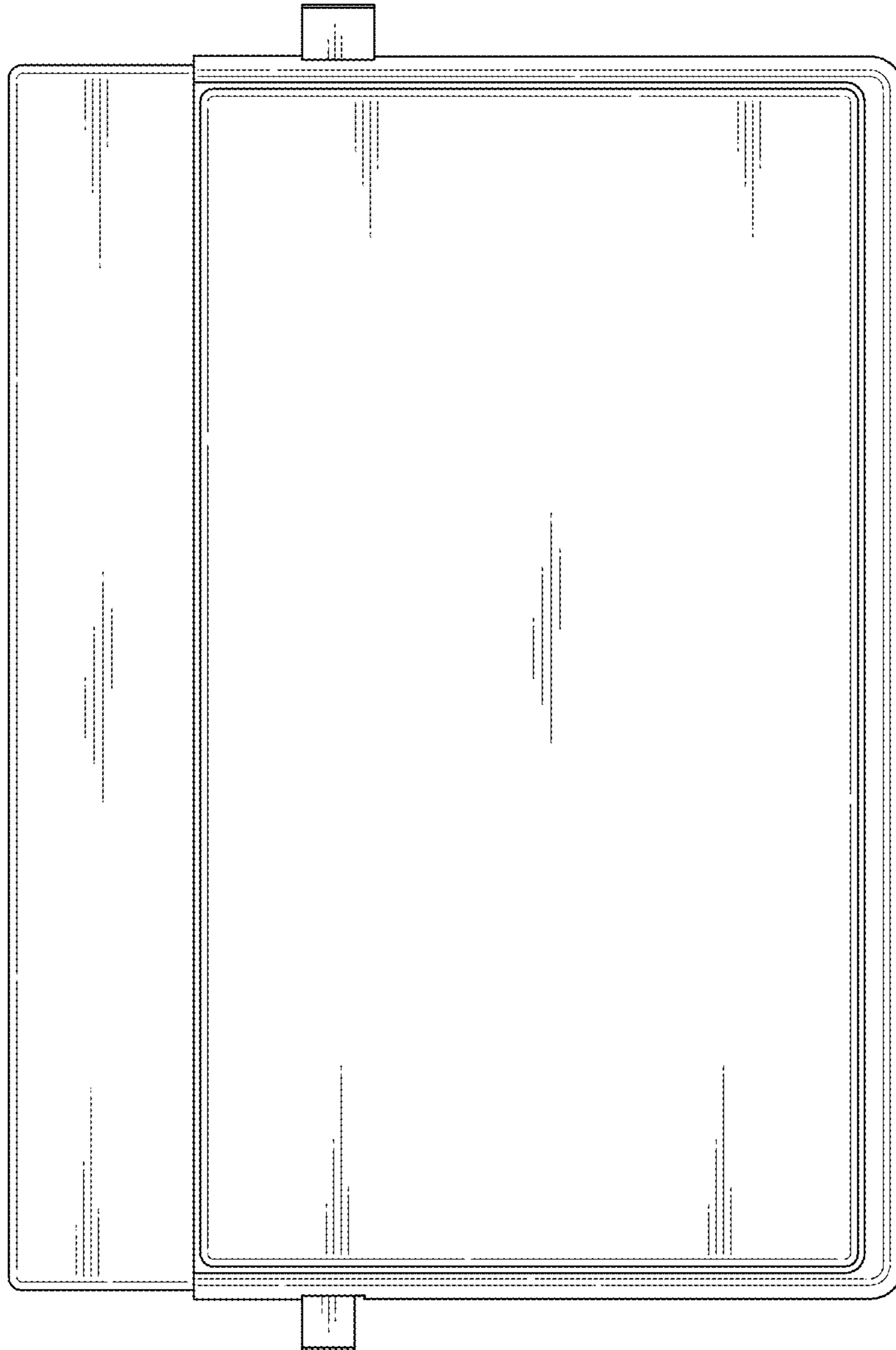




Fig. 5

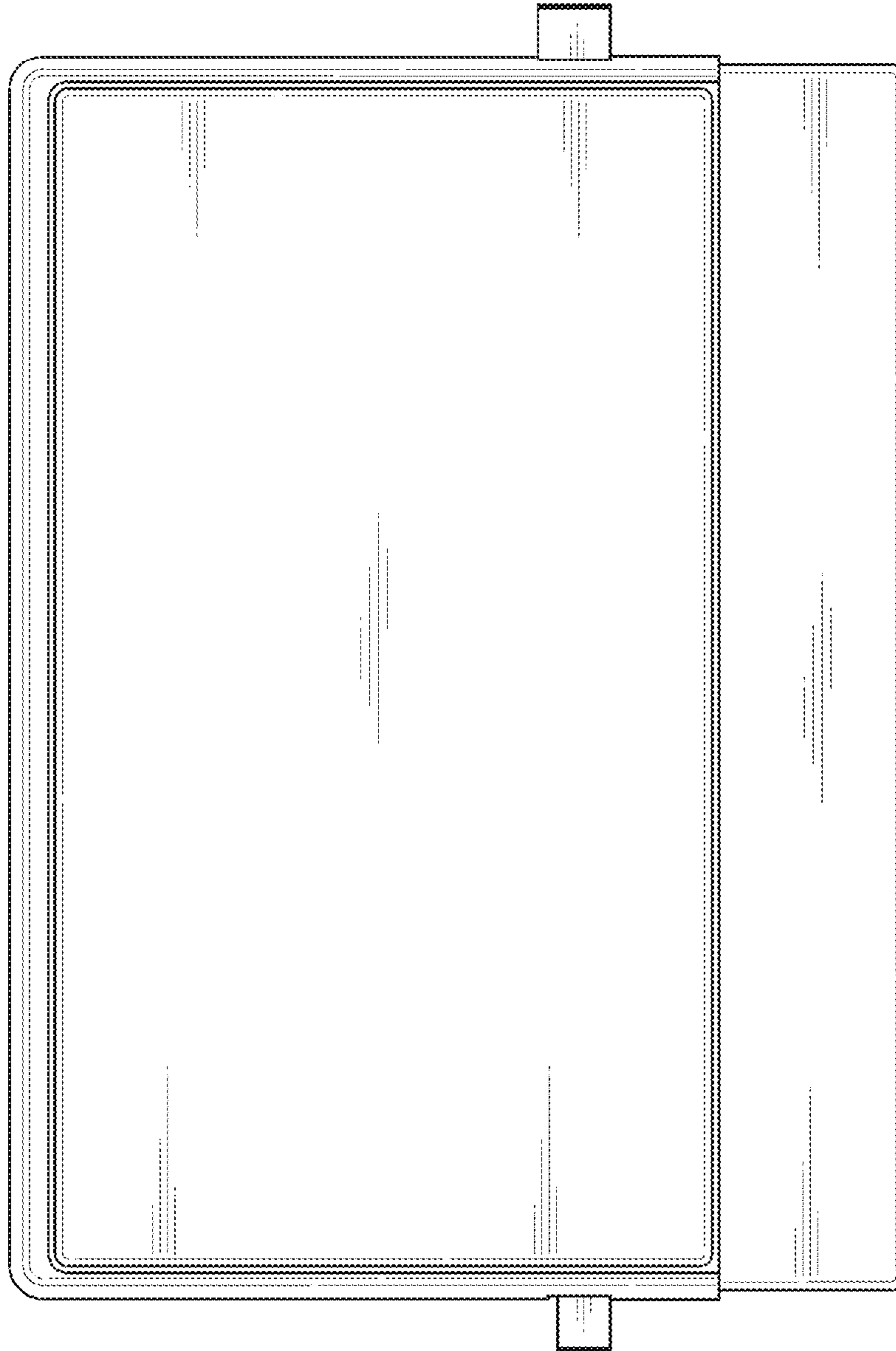


Fig. 6

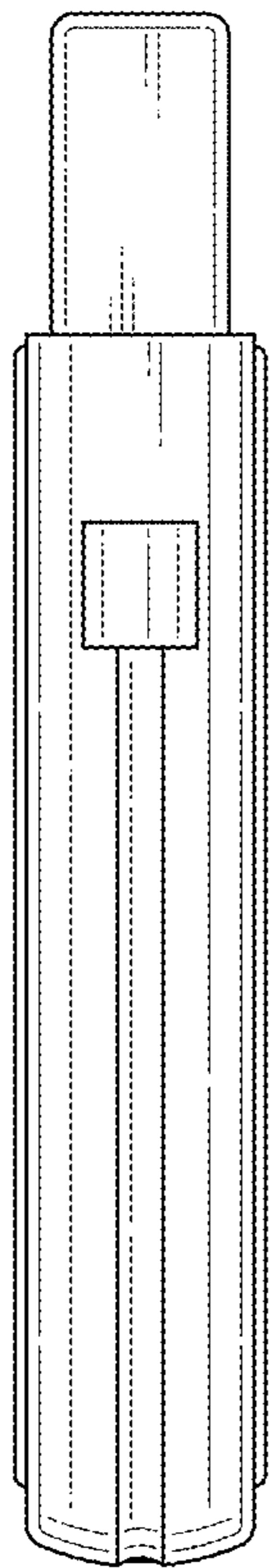


Fig. 7

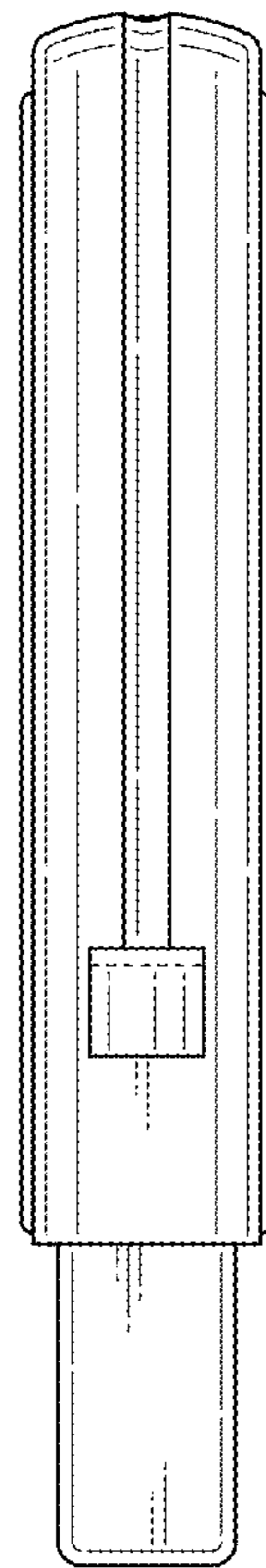


Fig. 8

